

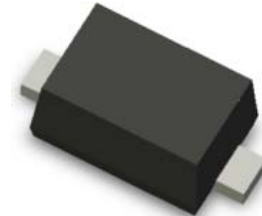
1N4148WT / 1N4448WT / 1N914BWT

High Conductance Fast Switching Diode

- Fast Switching Diode ($T_{rr} < 4.0\text{ns}$)
- Flat Lead, Surface Mount Device under 0.70mm Height
- Extremely Small Outline Plastic Package SOD523F
- Moisture Level Sensitivity 1
- Pb-free Version and RoHS Compliant
- Matte Tin (Sn) Lead Finish
- Green Mold Compound

Device Marking Code

Device Type	Device Marking
1N4148WT	E1
1N4448WT	E2
1N914BWT	E3



SOD-523F
Band Indicates Cathode*

Absolute Maximum Ratings* $T_a=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
V_{RSM}	Non-Repetitive Peak Reverse Voltage	75	V
V_{RRM}	Repetitive Peak Reverse Voltage	75	V
I_{FRM}	Repetitive Peak Forward Current	300	mA
T_J	Operating Junction Temperature Range	-55 to +150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to +150	$^\circ\text{C}$

* These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

NOTES:

- 1) These ratings are based on a maximum junction temperature of 150 degrees C.
- 2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Thermal Characteristics

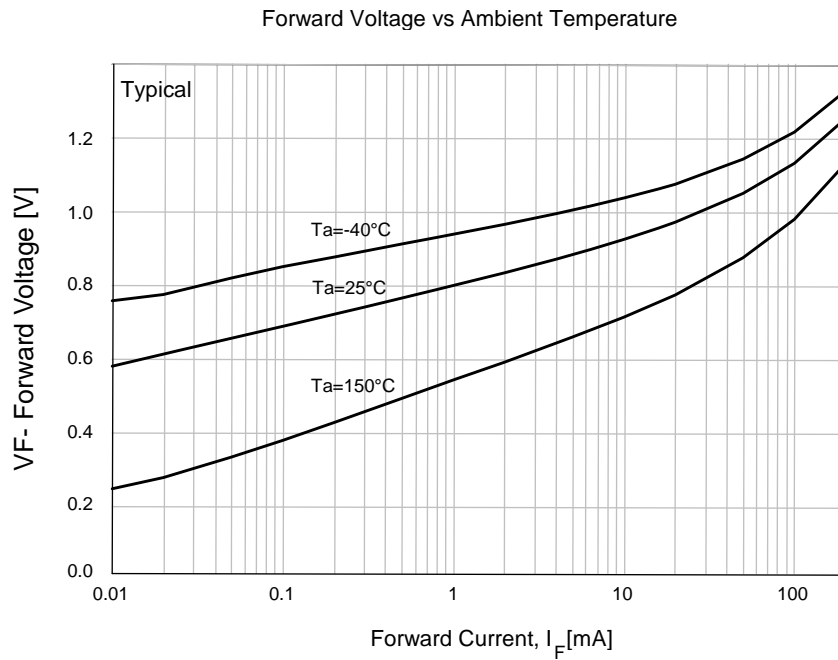
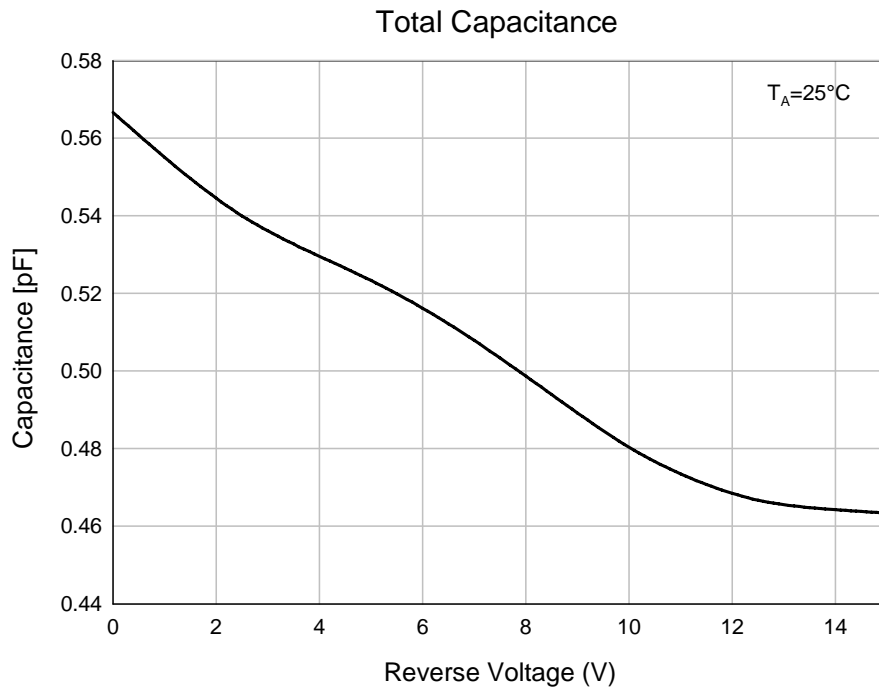
Symbol	Parameter	Value	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	500	$^\circ\text{C}/\text{W}$
P_D	Power Dissipation ($T_C=25^\circ\text{C}$)	200	mW

*Device mounted on FR-4 PCB minimum land pad.

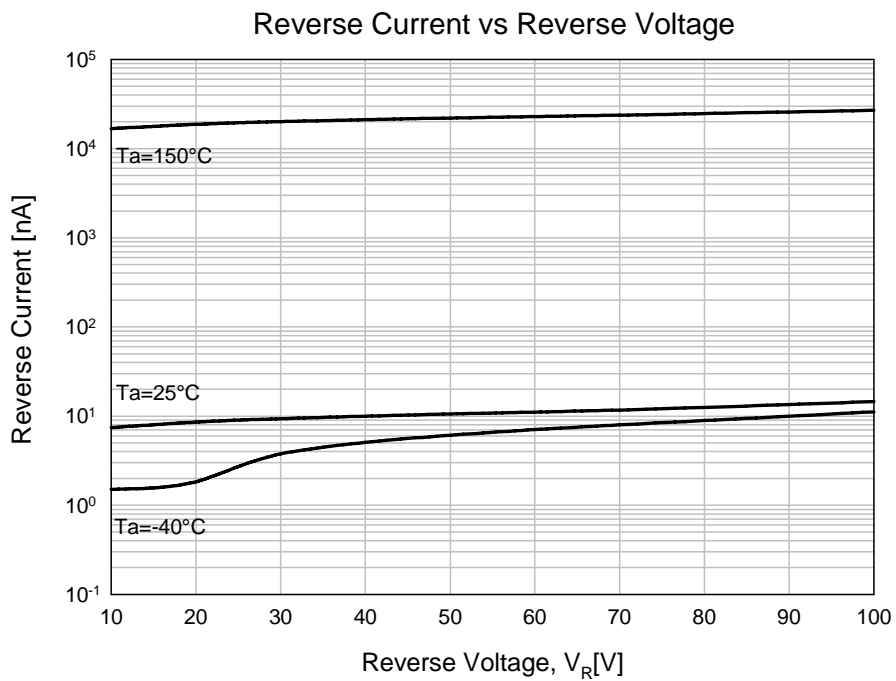
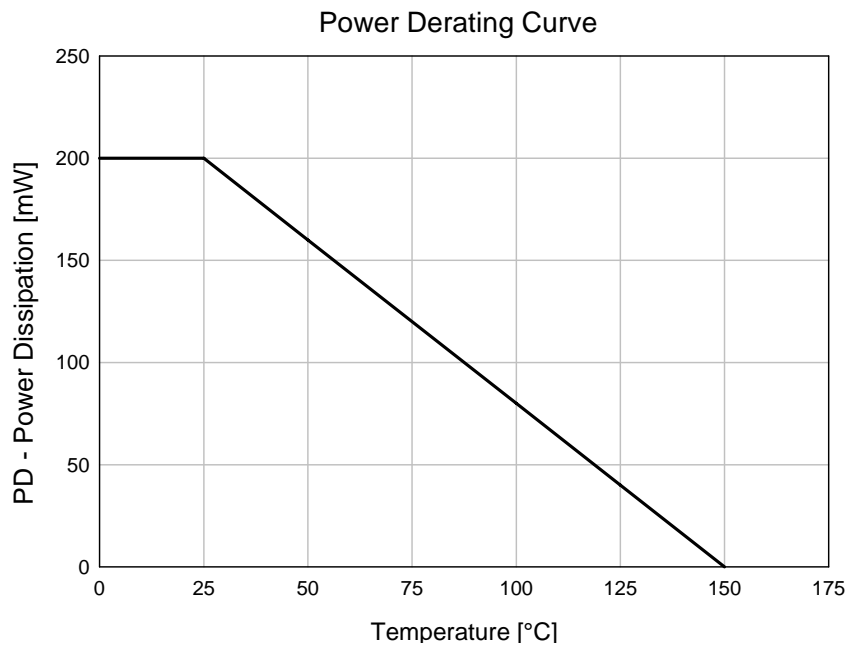
Electrical Characteristics* $T_a=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter		Test Conditions	Min	Typ	Max	Units
BV_R	Breakdown Voltage		$I_R = 100 \mu\text{A}$ $I_R = 5 \mu\text{A}$	100 75			V
I_R	Reverse Current		$V_R = 20 \text{V}$ $V_R = 75 \text{V}$			25 5	nA μA
V_F	Forward Voltage	1N4448WT/ 914WT 1N4448WT 1N4448WT/ 914WT	$I_F = 5 \text{mA}$ $I_F = 10 \text{mA}$ $I_F = 100 \text{mA}$	0.62		0.72 1 1	V
C_O	Diode Capacitance		$V_R = 0, f = 1 \text{MHz}$			4	pF
T_{RR}	Reverse Recovery Time		$I_F = 10 \text{mA}, V_R = 6.0 \text{V}$ $I_{RR} = 1 \text{mA}, R_L = 100 \Omega$			4	nS

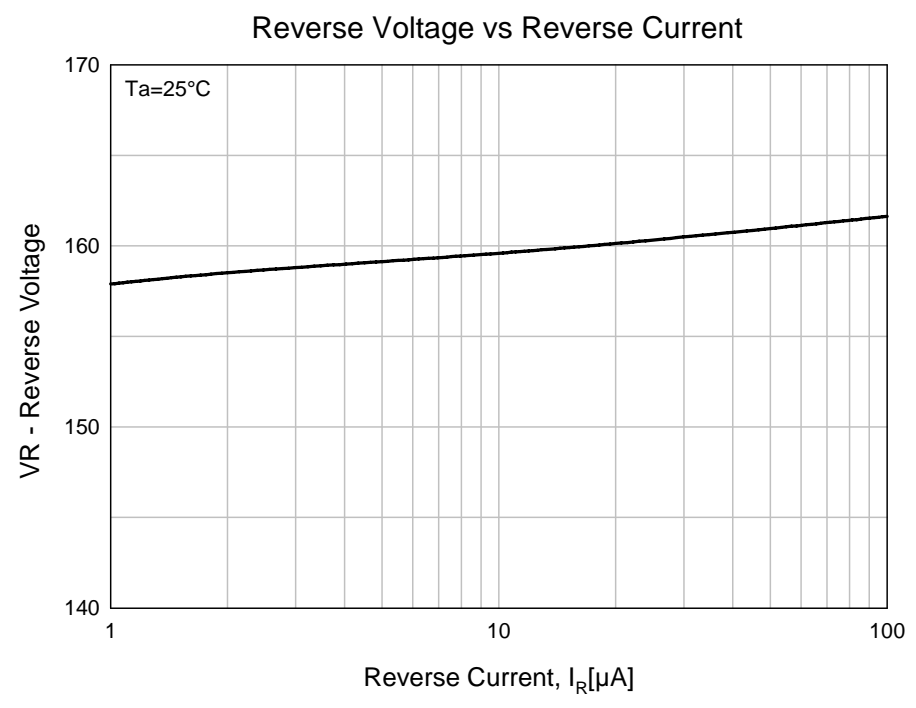
Typical Performance Characteristics



Typical Performance Characteristics

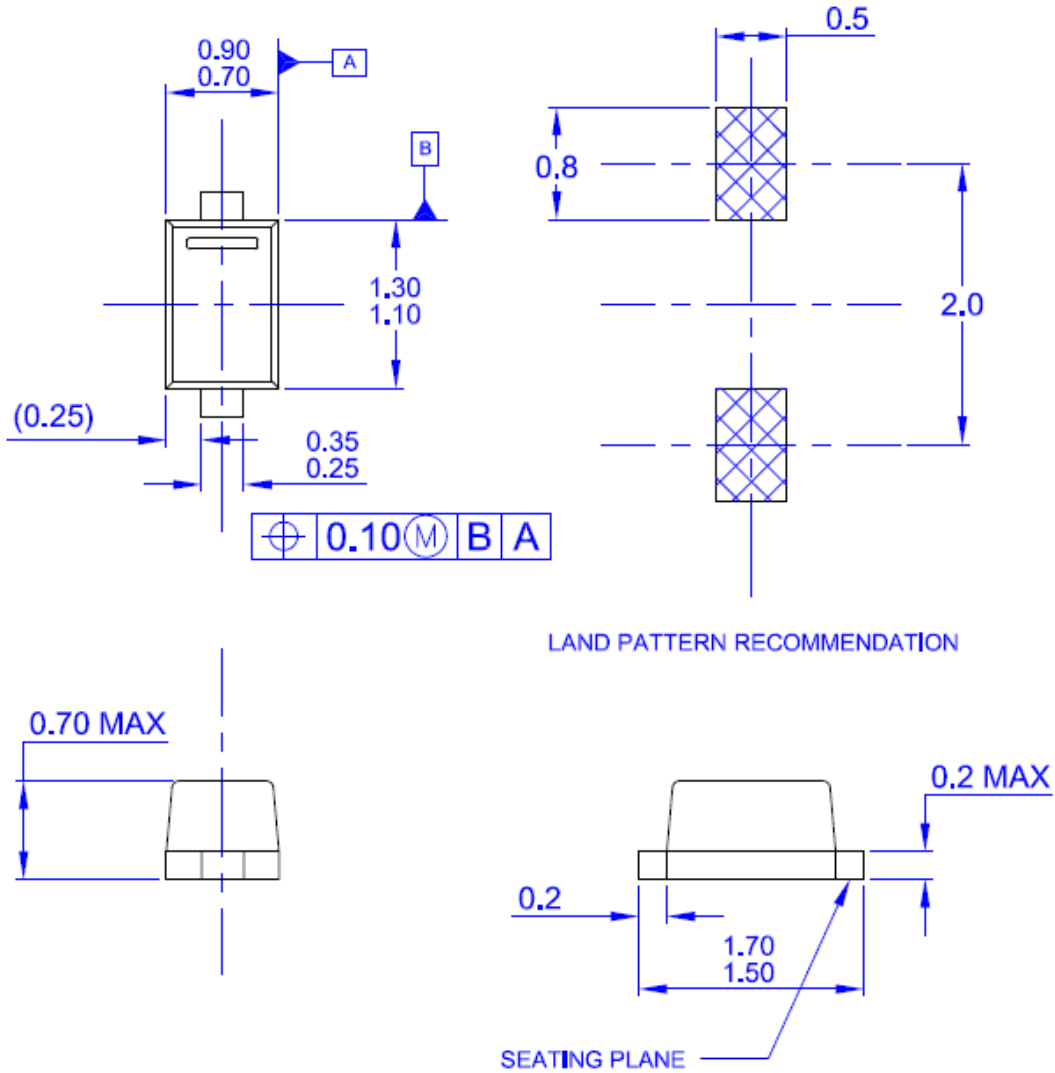


Typical Performance Characteristics



Package Dimension

SOD-523F



NOTES: UNLESS OTHERWISE SPECIFIED

- A) PACKAGE REFERENCE: THIS PACKAGE OUTLINE CONFORMS TO JEITA SC-79.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DRAWING CONFORMS TO ASME Y14.5M - 1994
- D) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- E) LANDPATTERN RECOMMENDATION IS BASED ON IPC7351A STANDARD SOD1609X65M.
- F) DRAWING NUMBER AND REVISION: MKT-SOD523F1rev1



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